Gas Discharge Tubes CG6 Series



RoHS

CG6 Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
91	E128662
91	E320116

Two Electrode GDT Graphical Symbol



Additional Information



Revised: 12/12/17





Description

The Littelfuse CG6 series GDT is a miniature surfacemount device with a 3kA 8/20 surge rating. This ITU-T K.12 Class 1, Type 1 GDT provides protection against fast rising transients typically caused by nearby lightning events. Its low insertion loss and thus low off-state capacitance makes it compatible with high bandwidth applications up to the GHz RF range. This GDT's crowbarring characteristic protects sensitive ICs from surges as defined in ITU K.20/21/45 Basic and Enhanced Recommendations, GR-1089-CORE first level lightning Port Type 1,3, and 5, and IEC 61000-4-5, 2nd edition Level 5 and below. It is hermetically sealed using non-radioactive materials and is thus environmentally safe.

Features

- RoHS compliant and Lead-free
- Excellent Surge Withstanding Capability
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss and low off-state capacitance for GHz bandwidth compatibility
- 3kA 8/20µs surge capability
- Broadband equipment
- CATV/Broadband
- Data lines and Ethernet (up to 10GbE)
- xDSL equipment, including ADSL2, ADSL, VDSL, VDSL2 30a bandplan compatible
- IAD (Integrated Access) Device)
- Set Top Box (STB)
- General telecom equipment

- Compact SMD package offered in two squared terminals
- Non-Radioactive
- Ultra Low capacitance (<0.3pF)
- Voltage Range 75V to 600V
- UL recognized

(EMTA)

 Characterized according to ITU-T K.12 as a Class X, Type 1 GDT

 Embedded Multimedia Terminal Adapter

Alliance (MoCA)

antenna transmitter

212 MHz bandplans

• G.Fast 106MHz and

Base Station RF

compatible

 Aerospace and Automotive

Applications

- equipment
 - RF Connector Multimedia over Coax

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Electrical Characteristics

	Device Specifications (at 25°C)						Life Ratings								
Part		Breakd in Volt @100V/s	S	Impulse Break- down in Volts (@100V/µs)	Impulse Break- down In Volts (@1 kV/µs)	Insulation Resistance	Capaci- tance (@1MHz)	Max Impulse Discharge Current ^(8/20µs)	Max Impulse Discharge Current (10/700µs)	AC Dischage Current (50Hz, 1sec)	AC Dischage Current (Single, 9 Cycles)	DC Holdover Voltage (<150ms)	Impulse Life (10/1000µs) (50A)		
Number	MIN	TYP	MAX	MAX		MIN	MAX			MIN	MIN		MIN		
CG675	60	75	90	600	700	1GΩ @50V		1GΩ						52V	
CG690	72	90	108	600	700								52V	1	
CG6145	116	145	174	600	700		10 Shots				52V]			
CG6230	186	230	276	600	700			10 Shots				80V	7		
CG6250	200	250	300	600	700	1GΩ @100V		0.0-4	(3kÅ) 1	10 Shots	2.4	C.A.	80V	300	
CG6300	240	300	360	650	800		0.3pf		@ (150A/6kV) ²	ЗA	6A	135V	Shots		
CG6350	280	350	420	750	900		@100V		1 Shot at 5kA				135V	1	
CG6400	360	400	480	850	1000				JKA				135V	1	
CG6470	376	470	564	900	1100							135V	1		
CG6600	480	600	720	1000	1200	1GΩ@250V						135V	1		

Note:

1. 5 x (+) and 5 x (-) applications of 3kA 8/20 μs sec.

Product Characteristics

2. 5 x (+) and 5 x (-) applications of 150A 10/700 μs sec.

Materials	Device Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator
Storage and Operational Temperature	-40 to +90°C

Typical Insertion Loss

@1.0GHz = 0.03dB
@1.4GHz = 0.06dB
@1.8GHz = 0.09dB
@2.0GHz = 0.11dB
@2.4GHz = 0.13dB
@2.8GHz = 0.15dB
@3.1GHz = 0.17dB
@3.5GHz = 0.19dB
@4.0GHz = 0.22dB

Note: Insertion data for customer reference only, application testing needed for verification.

V-I Characteristic Curve

Characteristics of Gas Plasma -response to transient condition



impedance state once the voltage across the device falls below this level.

Voltage Vs. Time Characteristic



Note: Tested per 1kV/µs waveform



Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Co	ndition	Pb – Free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Pre Heat	-Temperature Max (T _{s(max)})	200°C		
	-Time (Min to Max) (t _s)	60 – 180 secs		
Average ra (T _L) to pea	amp up rate (LiquidusTemp k	3°C/second max		
T _{S(max)} to T _L	- Ramp-up Rate	5°C/second max		
Reflow	-Temperature (T _L) (Liquidus)	217°C		
nellow	-Temperature (t _L)	60 – 150 seconds		
PeakTemp	erature (T _P)	260 ^{+0/-5} °C		
Time with Temperatu	in 5°C of actual peak ıre (t _p)	10 – 30 seconds		
Ramp-dov	vn Rate	6°C/second max		
Time 25°C	to peakTemperature (T _P)	8 minutes Max.		
Do not exc	ceed	260°C		



Device Dimensions





Recommended Soldering Pad Layout

Product Marking



Type Code					
Α	CG675				
В	CG690				
S	CG6145				
D	CG6230				
R	CG6250				
E	CG6300				
G	CG6350				
I	CG6400				
Р	CG6470				
V	CG6600				

Month Code				
Α	January			
В	February			
C	March			
D	April			
Е	May			
F	June			
G	July			
Н	August			
I	September			
J	October			
К	November			
L	December			



Taping and Reel Specifications

ltem	Spec Item		Spec	
Р	8.0 ± 0.1		Е	1.75 ± 0.1
P0	4.0 ± 0.1		D	1.50 + 0.1/-0.0
P2	2.0 ± 0.1		B0	4.5 ± 0.1
W	12.0 ± 0.3		KO	3.9 ± 0.1
F	5.5 ± 0.1		Т	0.4 ± 0.1
A0	3.9 ± 0.1		10P0	4.0 ± 0.2

330±4.0



Packaging Quantity: 2000 pcs per reel (13")

1 reels per inner box 10 inners box per carton 20,000 pcs per full carton





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